

Programming Overview

This document defines the programming specification for the dsPIC33AK256MPS306 Family Digital Signal Controller (DSC) devices:

- dsPIC33AK128MPS303
- dsPIC33AK128MPS305
- dsPIC33AK128MPS306
- dsPIC33AK256MPS303
- dsPIC33AK256MPS305
- dsPIC33AK256MPS306
- dsPIC33AK128MPS103
- dsPIC33AK128MPS105
- dsPIC33AK128MPS106
- dsPIC33AK256MPS103
- dsPIC33AK256MPS105
- dsPIC33AK256MPS106

The programming is implemented via the In-Circuit Serial Programming (ICSP™) interface, which includes the clock and data pins (PGECx and PGEDx).

The dsPIC33AK256MPS306 devices have a Nonvolatile Memory (NVM) controller module. This NVM module performs the device Flash memory programming. Its operation is configured and managed by the CPU. The external programmer tool uses the serial programming interface (ICSP) to shift in and execute CPU instructions, move data in and out of the device, and configure the NVM controller for programming operations. The programmer sends `MOV` instructions to the CPU to store (prepare) the Flash data to be programmed in the device RAM or NVM Control registers, depending on the Programming mode. Then, the programmer executes CPU instructions to initiate erase or write operations using the NVM controller. To read Flash data from the device, a VISI register is implemented. The content of this register can be shifted out to the ICSP interface. For fast Flash content verification, the NVM controller supports a CRC-32 checksum engine. It can reduce the amount of data which should be read over the ICSP communications pins. [Figure 1](#) explains the interactions between the programmer and the device.

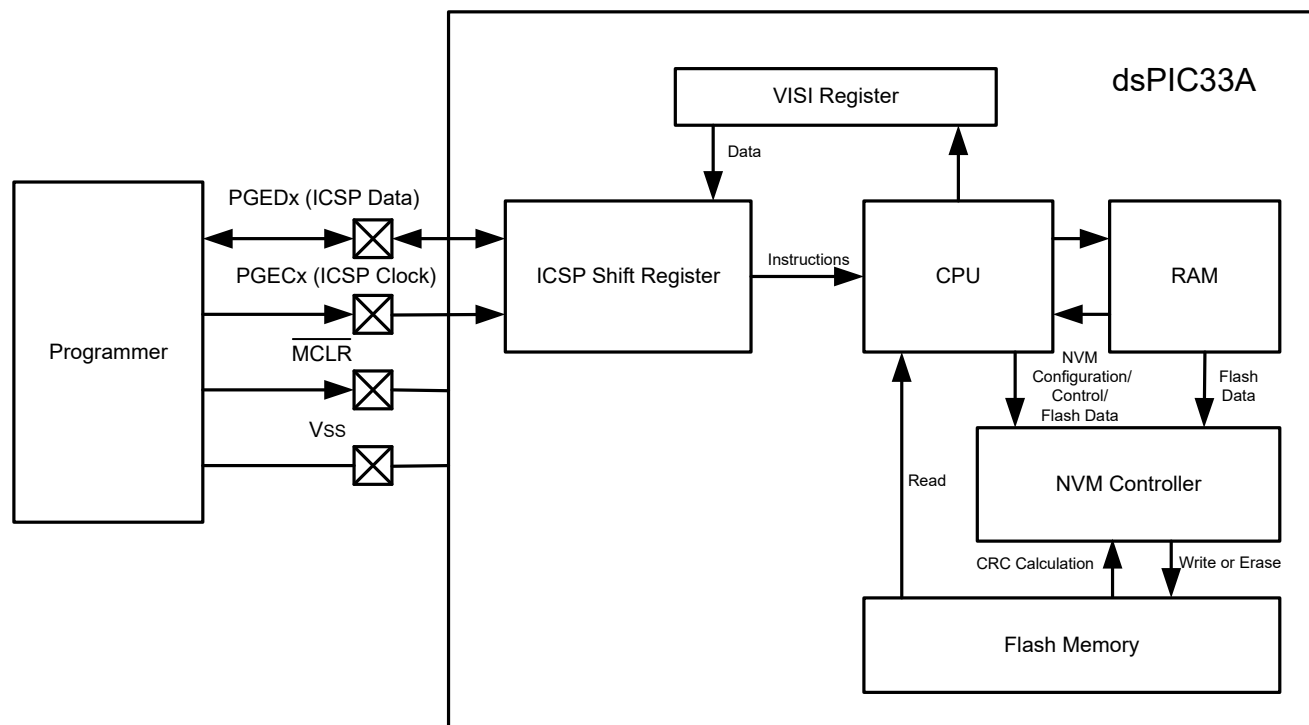
Figure 1. Programming Interactions Block Diagram

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1. Flash Memory

The Flash memory on dsPIC33AK256MPS306 family devices is divided into quadwords (16 bytes each), write rows (512 bytes each) and erase pages (4096 bytes each). The quadword (four 32-bit long words) is the minimum data size that can be written into the Flash. The address of each quadword is aligned by 16 bytes. The Flash memory can be written by rows, and each row consists of 32 quadwords or 512 bytes. The address of each row is aligned by 512-byte boundaries.

The Flash memory must be erased before a write operation can be initiated, and it can be erased by pages. Each erase page consists of eight rows or 4096 bytes. The address of each erase page is aligned by 4096-byte boundaries.

The dsPIC33AK256MPS306 family devices' Flash memory regions are shown in [Table 1-1](#).

Table 1-1. Flash Memory Map

Memory Region			Address	Number of Quadwords	Number of Write Rows	Number of Erase Pages	Description
User OTP			0x7F2C00-0x7F3000	64	2	Not applicable	Quadword or row programmed, never erasable
User Configuration A (UCA1)			0x7F3000-0x7F3FC	256	8	1	Bulk or page erased, quadword programmed
User Configuration B (UCB)			0x7F4000-0x7F4FC	256	8	1	
User Configuration A2 (UCA2)			0x7FB000-0x7FBFFC	256	8	1 ⁽¹⁾	
Code Memory	128-Kbyte Flash Memory Devices	Single Boot	800000-81FFFC	8182	256	32	Bulk or page erased, quadword or row programmed
		Dual Boot	800000-80FFFC	4091	128	16	
			C00000-C0FFFC	4091	128	16	
	256-Kbyte Flash Memory Devices	Single Boot	800000-83FFFC	16384	512	64	
		Dual Boot	800000-81FFFC	8182	256	32	
			C00000-C1FFFC	8182	256	32	
Note:							
1. UCA2 is used only when the device operates in a Dual Partition Flash mode. In Single Partition mode, only UCA1 is active.							

Some dsPIC33AK256MPS306 family device registers are used in the programming procedures. The descriptions and addresses of these registers are listed in [Table 1-2](#).

Table 1-2. Registers Used in the Programming Procedures

Register Name	Address	Description
VIS1	0x0007C0	This is a register to move (shift) data out of the device through the ICSP interface.
NVMCON	0x003000	This is a register to select type and initiate erase or write Flash operations.
NVMADR	0x003004	This register is the destination Flash address for erase or write operations.
NVMDATA0	0x003008	This is a register with data to be programmed to Flash when quadword write is used.
NVMDATA1	0x00300C	This is a register with data to be programmed to Flash when quadword write is used.

Table 1-2. Registers Used in the Programming Procedures (continued)

Register Name	Address	Description
NVMDATA2	0x003010	This is a register with data to be programmed to Flash when quadword write is used.
NVMDATA3	0x003014	This is a register with data to be programmed to Flash when quadword write is used.
NVMSRCADR	0x003018	This register should be set to the address of the RAM buffer loaded with the Flash row data to be programmed.
NVMCRCCON	0x003048	This register controls the Cyclic Redundancy Check (CRC) calculation of the Flash region.
NVMCR CST	0x00304C	This register contains the start address of the 4-Kbyte Flash memory block for the CRC calculation.
NVMCR CEND	0x003050	This register contains the end address of the 4-Kbyte Flash memory block minus one byte for the CRC calculation.
NVMCR CSEED	0x003054	The initial CRC value (seed) should be loaded into this register. If the CRC-32 is calculated for the multiple memory blocks, then the previous CRC result must be written directly to NVMCR CSEED before the next block of CRC calculations.
NVMCR CDATA	0x003058	This register contains the CRC calculation result.

1.1. Flash Memory Controller

This Flash (or NVM) controller module performs the erase or write operations of the device Flash memory. The programming configuration and status are provided in the NVMCON register. The NVMOP bits in the NVMCON register select the operation type. The descriptions of the available operations are listed in [Table 1-3](#).

Table 1-3. Programming Operations

Type of Operation	NVMOP Bits (NVMCON[3:0]) Value	Description
Bulk Erase	1110	Erases the entire code and Configuration bits' memories. OTP area(s) are not erased.
Inactive Partition Erase	0100	Erases the Inactive Partition.
Page Erase	0011	Erases a page of code or Configuration memory. The address of the Flash page must be specified in the NVMADR register. NVMADR[11:0] are ignored (treated as all '0's) for this NVMOP, hardware enforcing 4096-byte page alignment.
Row Write	0010	Writes a row of code or Configuration memory. The address of the Flash row must be specified in the NVMADR register. The row data must be stored (prepared) in RAM. The address of the Flash data RAM buffer must be specified in the NVMSRCADR register. The Flash memory must be erased before the write operation. NVMADR[8:0] are hardware ignored, enforcing 512-byte destination row alignment. NVMSRCADR[1:0] are unimplemented, so source data in RAM must start on a 32-bit long word-aligned boundary.

Table 1-3. Programming Operations (continued)

Type of Operation	NVMOP Bits (NVMCON[3:0]) Value	Description
Quadword Write	0001	Writes four 32-bit long words of code, OTP or Configuration memory. The address of the Flash location to be written must be specified in the NVMADR register. The data must be stored (prepared) in the NVMDATA0, NVMDATA1, NVMDATA2 and NVMDATA3 registers. The Flash memory must be erased before the write operation. NVMADR[3:0] are unimplemented, enforcing 16-byte quadword address alignment.

Perform the following steps to erase or write the Flash memory:

1. Set the destination address to be erased or written in the NVMADR register.
2. Load data for the write operation in the NVMDATA0-NVMDATA3 registers or in a RAM buffer located by the address in the NVMSRCADR register.
3. Select the programming operation with the NVMOPx bits (NVMCON[3:0]).
4. Enable the NVM module operation by setting the WREN bit (NVMCON[14]).
5. Initiate the operation selected by setting the WR bit (NVMCON[15]).
6. Read/poll the WR bit (NVMCON[15]). The WR bit remains set while the erase or write operation is still in progress. Hardware clears this bit when the operation has completed.

The full description of the NVM controller and the programming details can be found in the device data sheet.

Also, the NVM controller can calculate a 32-bit Cyclic Redundancy Check (CRC) checksum. This checksum can be used to verify the result of Flash erase or programming. The start and end addresses of the Flash region are 4-Kbyte (page) aligned. The CRC can be calculated even while the Flash region is protected from data read back.

Perform the following steps to get the CRC checksum:

1. Write the start address into the NVMCR CST register.
2. Write the end address into the NVMCR CEND register.
3. Enable the CRC by setting the CRCEN bit (NVMCRCCON[15]).
4. Start the calculation by setting the START bit (NVMCRCCON[14]).
5. Read/poll the START bit (NVMCRCCON[14]). This bit is cleared when the CRC checksum is ready.
6. Read the CRC result from the NVMCR CDATA register.

Though the device hardware implements a parallel CRC-32 algorithm of the calculations, the same result can be achieved in the software by an algorithm using a 32-bit Shift register. The pseudocode in [Example 1-1](#) explains the Shift register algorithm.

Example 1-1. Shift Register CRC Calculation Algorithm

```
// Initialize shift register
SeedValue(31:0) = 0
ShiftRegister(31:0) = INVERT SeedValue(31:0)
REPEAT FOR ALL DATA WORDS
  REPEAT 32 TIMES
    // Exclusive OR of data bit 31 and shift register bit 0
    CRCNext = DataWord(31) EXOR ShiftRegister(0)
    // Shift the register right
    ShiftRegister(30:0) = ShiftRegister(31:1)
    ShiftRegister(31) = 0
    // Shift data left to process the next bit of the word
    DataWord(31:1) = DataWord(30:0)
    IF CRCNext != 0 THEN
      // Exclusive OR with polynomial
      ShiftRegister(31:0) = ShiftRegister(31:0) EXOR 0xEDB88320
    ENDIF
  ENDREPEAT
```

```
ENDREPEAT
CRCResult = INVERT ShiftRegister(31:0)
```

Where:

- SeedValue[31:0] – Initial CRC value written into the NVMCRCSEED register
- DataWord[31:0] – Current data word for the CRC calculation
- CRCResult[31:0] – CRC checksum result in the NVMCRCDATA register

1.2. Device ID (DEVID)

Each device variant with a different memory size and package option can be identified by a device ID located in the DEVID register. The device revision is stored in the REVID register. These register addresses are shown in [Table 1-4](#).

Table 1-4. Device ID and Revision Registers

Register Name	Address	Description
DEVID	0x7C2000	Device ID (device variant)
REVID	0x7C2004	Device revision

The device ID values for each memory and pin count variant are listed in [Table 1-5](#).

Table 1-5. Device ID Values

Device	Device ID Value
dsPIC33AK128MPS303	0xB514
dsPIC33AK128MPS305	0xB515
dsPIC33AK128MPS306	0xB516
dsPIC33AK256MPS303	0xB51C
dsPIC33AK256MPS305	0xB51D
dsPIC33AK256MPS306	0xB51E
dsPIC33AK128MPS103	0xB504
dsPIC33AK128MPS105	0xB505
dsPIC33AK128MPS106	0xB506
dsPIC33AK256MPS103	0xB50C
dsPIC33AK256MPS105	0xB50D
dsPIC33AK256MPS106	0xB50E

1.3. Unique Device ID (UDID)

All dsPIC33AK256MPS306 family devices are individually encoded during final manufacturing with a Unique Device Identifier or UDID. The UDID cannot be erased by a Bulk Erase command or any other user-accessible means. This feature allows for manufacturing traceability of Microchip Technology devices in applications where this is a requirement. It may also be used by the application manufacturer for any number of things that may require unique identification, such as:

- Tracking the device
- Unique serial number
- Unique security key

The UDID comprises four 32-bit program words. When taken together, these fields form a unique 128-bit identifier. The UDID is stored in four read-only locations in the device configuration space. [Table 1-6](#) lists the UDID words.

Table 1-6. UDID Words

Register Name	Address	Description
UDID1	0x7F2BE0	UDID bits from 0 to 31
UDID2	0x7F2BE4	UDID bits from 32 to 63
UDID3	0x7F2BE8	UDID bits from 64 to 95
UDID4	0x7F2BEC	UDID bits from 96 to 127

1.4. Configuration Bits

The Configuration bits are stored in the User Configuration A and User Configuration B Flash memory areas. These bits can be programmed (= 0) or erased (= 1) to select various device configurations. There are two types of Configuration bits: system operation bits and code-protect bits. The system operation bits determine the power-on settings for system-level components, such as the Watchdog Timer. The code-protect bits prevent program memory from being read and written. [Table 1-7](#) lists the Configuration Words of the dsPIC33AK256MPS306 family devices. Refer to the device data sheet for the full Configuration Word register descriptions. In addition, both the two regions (in single boot) and the three regions (in dual boot) also have a backup copy. The configuration data are automatically loaded from the Flash Configuration Words to the proper Configuration Shadow registers during device Resets. The locations of the CFGA1, CFGA2 and CFGB registers and their backups are shown in [Table 1-7](#). The primary and backup registers should be programmed at the same time or following the order described in [Programming in Dual Partition Mode](#).

Table 1-7. Configuration Words

Configuration Word Name	Address	Backup Location Address	Configuration Area	Description
FCP	0x7F3000	0x7F3800	UCA1 ⁽¹⁾	This Configuration Word enables the Flash protection.
FICD	0x7F3010	0x7F3810		Debugger Configuration register.
FDEVOP	0x7F3020	0x7F3820		This word configures some peripherals' features.
FWDT	0x7F3030	0x7F3830		This Configuration Word controls the Watchdog Timer.

Note:

1. When operating in Dual Boot mode, Dual Boot Devices have two UCA pages: UCA1 for partition1 and UCA2 for partition2.

Table 1-7. Configuration Words (continued)

Configuration Word Name	Address	Backup Location Address	Configurati on Area	Description
FPRCTRL0	0x7F4000	0x7F4800	UCB	These Configuration Words allow definitions of up to eight memory regions with limitations on different Flash operations. FPRCTRLx Word enables the region and specifies what kind of Flash access should be restricted (erase, programming, reading, CRC calculation and so on). FPRSTx and FPRENDx should be programmed with the addresses of the first and last 4-Kbyte pages included in the region.
FPRST0	0x7F4004	0x7F4804		
FPREND0	0x7F4008	0x7F4808		
FPRCTRL1	0x7F4010	0x7F4810		
FPRST1	0x7F4014	0x7F4814		
FPREND1	0x7F4018	0x7F4818		
FPRCTRL2	0x7F4020	0x7F4820		
FPRST2	0x7F4024	0x7F4824		
FPREND2	0x7F4028	0x7F4828		
FPRCTRL3	0x7F4030	0x7F4830		
FPRST3	0x7F4034	0x7F4834		
FPREND3	0x7F4038	0x7F4838		
FPRCTRL4	0x7F4040	0x7F4840		
FPRST4	0x7F4044	0x7F4844		
FPREND4	0x7F4048	0x7F4848		
FPRCTRL5	0x7F4050	0x7F4850		
FPRST5	0x7F4054	0x7F4854		
FPREND5	0x7F4058	0x7F4858		
FPRCTRL6	0x7F4060	0x7F4860		
FPRST6	0x7F4064	0x7F4864		
FPREND6	0x7F4068	0x7F4868		
FPRCTRL7	0x7F4070	0x7F4870		
FPRST7	0x7F4074	0x7F4874		
FPREND7	0x7F4078	0x7F4878		
FIRT	0x7F4080	0x7F4880		This word enables the Immutable Root of Trust Regions mode.
FSECDBG	0x7F4090	0x7F4890		This word enables the Secure Debug mode.
FTPED	0x7F40A0	0x7F48A0		This word allows permanently disabling chip erase and external programming.
FEPUCB	0x7F40B0	0x7F48B0		Writing 0x84C1F396 in this Configuration Word disables the erase operation on the UCB area.
FWPUCB	0x7F40C0	0x7F48C0		Writing 0x5B9B12E4 in this Configuration Word disables the programming operation on the UCB area.
FBOOT	0x7F40D0	0x7F48D0		This word allows the selection between Single and Dual Boot modes.

Note:

1. When operating in Dual Boot mode, Dual Boot Devices have two UCA pages: UCA1 for partition1 and UCA2 for partition2.

Table 1-7. Configuration Words (continued)

Configuration Word Name	Address	Backup Location Address	Configuration Area	Description
FCP	0x7FB000	0x7FB800	UCA2 ⁽¹⁾	This Configuration Word enables the Flash protection.
FICD	0x7FB010	0x7FB810		Debugger Configuration register.
FDEVOPT	0x7FB020	0x7FB820		This word configures some peripherals' features.
WDT	0x7FB030	0x7FB830		This Configuration Word controls the Watchdog Timer.

Note:

1. When operating in Dual Boot mode, Dual Boot Devices have two UCA pages: UCA1 for partition1 and UCA2 for partition2.

1.5. Flash Memory Protection

The Configuration Words in User Configuration A (UCAx) and User Configuration B (UCB) Flash areas can restrict Flash operations over the entire Flash or defined memory regions. Refer to the device data sheet for a detailed description.

The NVM controller can calculate a CRC-32 checksum, even if the read operation is disabled for the Flash region, unless the CRC operation is also disabled.

1.5.1. Protected Regions

Up to eight protected regions can be created in the Flash memory. The start address, end address and region type are defined by the Configuration Words in UCB memory. The protected region can be configured to restrict read, write, erase (OTP) or CRC calculation by the NVM module.

1.5.2. User Configuration A and B Areas Protection

The FCP Configuration Word, located in UCAx, has WPUCA bits which can disable Page Erase and Write operations on the UCAx area. The UCAx area is always erased on Bulk Erase.

Two Configuration Words located in the UCB area, if programmed with special keys, disable erase or write operations on the UCB area. FEPUCB, when programmed with 0x84C1F396, permanently disables all ability to erase the UCB page via both Bulk Erase and Page Erase NVM commands. FWPUCB, when programmed with 0x5B9B12E4, permanently disables all ability to write further data to the UCB page. FEPUCB Erase Protection and FWPUCB Write Protection apply to both ICSP and Run-Time Self Programming code execution. If both the UCB Program and Erase Protection are activated, it permanently prevents UCB programming and erase operations, and it cannot be deactivated.

1.5.3. Entire Flash Protection

The FCP Configuration Word, located in the UCAx area, allows protection of the entire Flash from ICSP read-back (CP bit) and CRC calculations by the NVM module (CRC bit).

The FPED Configuration Word in the UCB area has the PED bit, which disables Bulk Erase, Page Erase, Row and Quadword Write for the entire device Flash. When this feature is enabled (PED bit = 0), it restricts all modification of the user Flash, User OTP and UCAx/UCB Configuration pages in ICSP mode. Run-Time Self-Programming code execution is unaffected by PED.

When this Program or Erase Protection feature (PED bit = 0) is used with UCB Erase Protection (FEPUCB word is 0x84C1F396), once activated, it permanently prevents the entire Flash ICSP programming and erase operations, and it cannot be deactivated.

1.6. Programming the FBOOT Configuration Register

Before the code memory, Configuration registers and user OTP are programmed, the FBOOT Configuration register (located at address, 0x7F40D0) must be programmed in order to configure the device in one of the Dual Partition Flash modes. The BTMODE[1:0] bits cannot be written as '00' (Reserved) or as '11' (Single Partition Flash). Single Partition Flash mode must be set by erasing the FBOOT register.

1.7. Dual Partition Flash Programming Considerations

The dsPIC33AK256MPS306 family of devices supports a Single Partition Flash mode and two Dual Partition Flash modes. The Dual Partition Flash modes allow the device to be programmed with two separate applications to facilitate bootloading or to allow an application to be programmed at run time without stalling the CPU.

The device's Boot mode is determined by the BTMODE[1:0] bits in the FBOOT Configuration register (see [Table 1-8](#)). The device will automatically check FBOOT on Reset and determine the appropriate Boot mode.

Table 1-8. Boot Mode Select

FBOOT[1:0]	Boot Mode
11	Single Partition Flash mode (default)
10	Dual Partition Flash mode
01	Protected Dual Partition Flash mode
00	Reserved

Protected Dual Partition Flash mode prevents run-time programming and erase functions for partition 1. ICSP modes are not affected.

1.7.1. Dual Partition Memory Organization

In the Dual Partition Flash modes, the device's memory is divided evenly into two physical sections, known as partition 1 and partition 2. Each of these partitions contains its own program memory and Configuration Words. During the program execution, the code on only one of these partitions can be executed and that will be the active partition. The other partition, or the inactive partition, cannot be used for execution but can be programmed.

The active partition is always mapped to program address, 0x800000, while the inactive partition will always be mapped to program address, 0xC00000. Even when the code partitions are switched between active and inactive by the user, the address of the active partition will still be 0x800000, and the address of the inactive partition will be 0xC00000.

The Boot Sequence Configuration Word (FBTSEQ) determines whether partition 1 or partition 2 will be active after Reset. If the part is operating in Dual Partition mode, the partition with the lower boot sequence number will operate as the active partition (FBTSEQ is unused in Single Partition mode). The partitions can be switched between active and inactive by reprogramming their boot sequence numbers, but the active partition will not change until a device Reset is performed. If both the boot sequence numbers are the same, or if both are corrupted, the part will use partition 1 as the active partition. If only one boot sequence number is corrupted, the device will use the partition without a corrupted boot sequence number as the active partition.

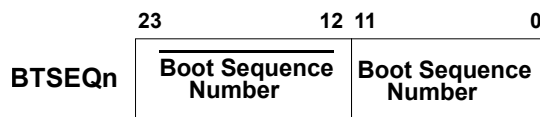
The user can also change which partition is active at run time using the `BOOTSWP` instruction. The `BOOTSWP` instruction must be enabled before it can be used (located in the FICD Configuration Word). Issuing a `BOOTSWP` instruction does not affect which partition will be the active partition after a Reset. [Figure 1-2](#) shows how partitions 1 and 2 are swapped between the active and inactive partitions during FBTSEQ reprogramming and `BOOTSWP` execution, respectively.

The P2ACTIV bit (NVMCON[10]) can be used to determine which physical partition is the active partition. If P2ACTIV = 1, partition 2 is active; if P2ACTIV = 0, partition 1 is active.

1.7.2. Dual Boot Sequence Number

The sequence number is stored in the legacy location in the last row of user Flash in the active panel and in the inactive panel.

When configured for a Dual Boot mode, after a Reset, the NVM Controller reads the boot sequence numbers contained in the BTSEQn words which are the last 128-bit Flash words of each user program partition. It compares the sequence numbers and maps the partition with the lowest sequence number into the active space. The other partition is mapped into the inactive space. The current mapping is indicated by the NVMCON.P2ACTIV bit. The boot sequence number is a 12-bit unsigned value. The BTSEQn word format consists of a two 12-bit values with BTSEQn[11:0] containing the true sequence number and BTSEQn[23:12] containing its complement as shown in [Figure 1-1](#).

Figure 1-1. Boot Sequence Number Word

BTSEQn[127:24] is reserved. A boot sequence number word is considered to be invalid if either:

- BTSEQn[11:0] != ~BTSEQn[23:12]
– OR –
- The boot sequence number word read results an ECC DED error.

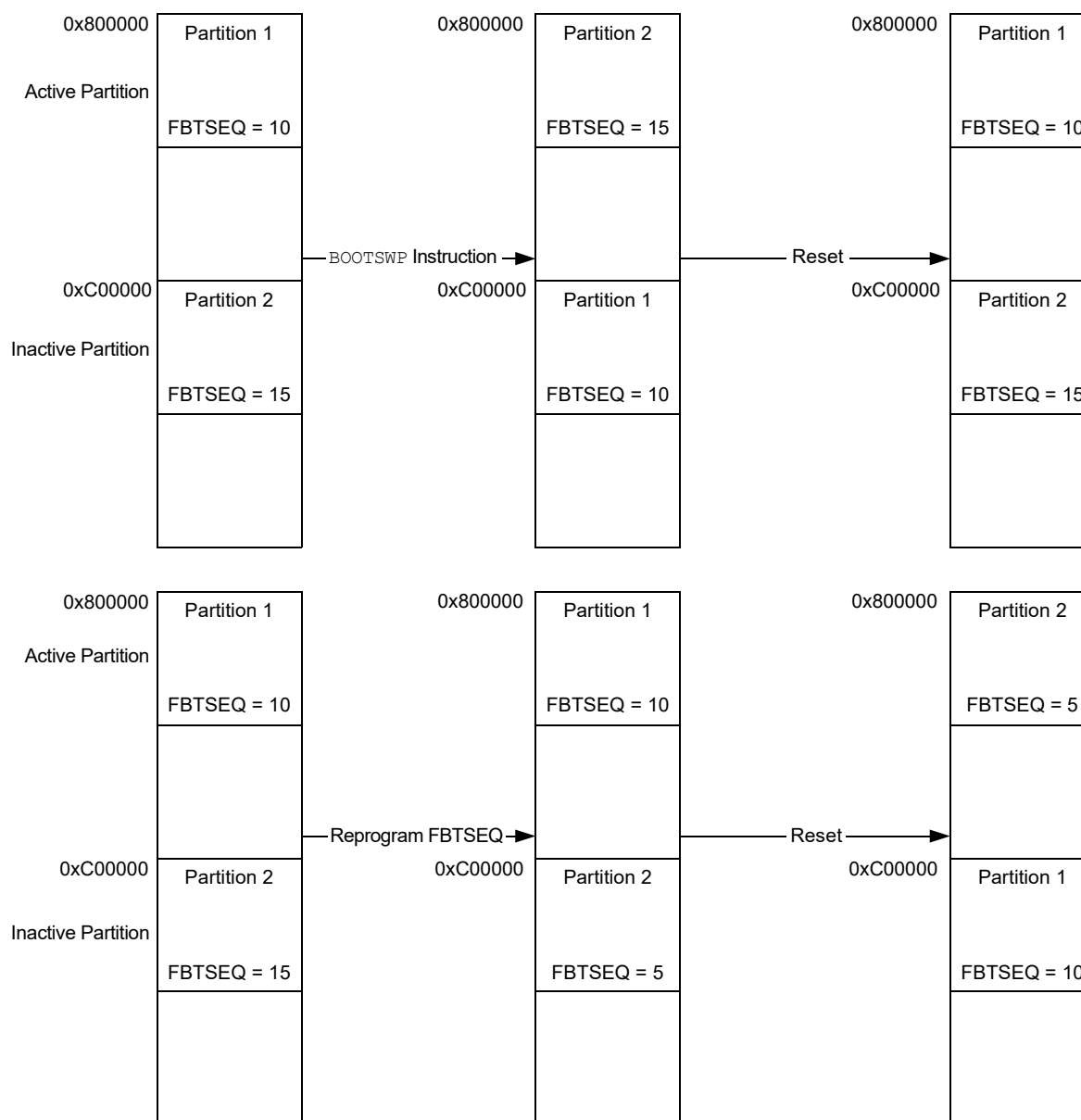
If a BTSEQn word is not valid, the boot sequence number for that partition is assigned the value 0xFFF. This is the highest possible boot sequence number. An unprogrammed word will yield an invalid boot sequence number. After determining the boot sequence numbers for each partition, the NVM Controller compares the boot sequence numbers and maps the partition with the lowest boot sequence number into the active space and maps the other partition into the inactive space. If the boot sequence numbers are equal, partition 1 is mapped into the active space. When re-flashing or updating firmware in a device configured for a Dual Boot mode, the programmer or mission mode firmware programs the inactive partition boot sequence number with a value lower than the active partition boot sequence number. Upon a subsequent Reset, the device will execute the new firmware.

1.7.3. Erase Operation with Dual Partition Flash

dsPIC33AK256MPS306 family devices support the following three erase operations: Bulk Erase, Inactive Partition Erase and Page Erase.

A Bulk Erase operation erases all user memory, including the Flash Configuration Words and the FBOOT Configuration register. This restores the Boot mode of the device to its default, Single Partition mode after Reset.

An Inactive Partition Erase operation can be executed at run time from the active partition. It will erase all user memory and Flash Configuration Words in the inactive partition. The Inactive Partition Erase command is functional only when the device is in one of the Dual Partition modes.

Figure 1-2. Relationship Between Partitions 1 and 2 and Active/Inactive Partitions

1.7.4. Dual Partition Configuration Words

In Dual Partition modes, each partition has its own set of Flash Configuration Words. The full set of Configuration registers in the active partition is used to determine the device's configuration. The Configuration Words in the inactive partition are not used until FBTSEQ is programmed for it to be the active partition, and a Reset occurs. The `BOOTSWP` instruction does not change the device's effective configuration based on the newly active partition's Configuration Words.

1.7.5. Programming in Dual Partition Mode

The following steps are required to program dsPIC33AK256MPS306 devices with dual partition Flash:

1. Perform a bulk erase of user program memory:

1. Enter ICSP mode.
2. Bulk Erase.
3. Exit ICSP.
2. Enter ICSP mode so that the program memory address map starts at a known state:
 - a. Enter ICSP mode.
3. Execute a page erase for UCA1, UCA2 and UCB:
 - a. Bulk Erase.
 - b. Exit ICSP.
4. Program the FBOOT backup register location and then the FBOOT register to one of the Dual Partition modes:
 - a. Enter ICSP mode.
 - b. Program FBOOT_BACKUP.
 - c. Exit ICSP mode.
 - d. Enter ICSP mode.
 - e. Program FBOOT.
 - f. Exit ICSP mode.
5. Issue a device Reset. This will split the memory into two partitions.
6. Enter ICSP mode:
 - a. Program the first application, including its boot sequence number, into the active partition at address, 0x800000.
 - b. Program the second application, including its boot sequence number, into the inactive partition at address, 0xC00000.
 - c. Write User Configuration A1 backup memory.
 - d. Write User Configuration A2 backup memory.
 - e. Write User Configuration B backup memory.
 - f. Write User Configuration A1 primary memory.
 - g. Write User Configuration A2 primary memory.
 - h. Write User Configuration B primary memory.
 - i. Exit ICSP mode.

1.8. Flash Memory Operations Timing

The maximum time for the Flash operations can be found in [Table 1-9](#).

Table 1-9. Flash Operations Maximum Time

Flash Operation	Maximum Time
Bulk Erase (no permanent regions defined)	80 mS
Bulk Erase (permanent regions defined)	20 mS x (number of erasable Flash pages) + 40 mS
Page Erase	20 mS
Quadword Programming	15 μ S
Row Programming	500 μ S

2. In-Circuit Serial Programming (ICSP™)

The In-Circuit Serial Programming (ICSP) mode allows shifting in and executing CPU instructions, and reading VISI register content through the PGECx/PGEDx pins. The PGECx is a serial clock signal, and PGEDx is a data signal.

2.1. Connections Required for ICSP

For ICSP operations, the device must be powered using all power and ground pins available on the package. The device internal circuits are powered from a core voltage regulator (buck converter). The buck converter requires two external components: 10 μ H inductor and 4.7 μ F ceramic capacitors which should be connected to V_{DDCORE} and L_X pins as shown in [Figure 2-1](#).

In addition to the power pins, the programming interface includes the $\overline{MCLR}$ (Reset) and one ICSP programming pin pair (PGEDx/PGECx). All dsPIC33AK256MPS306 devices have three separate pairs of programming pins, labeled as PGEC1/PGED1, PGEC2/PGED2 and PGEC3/PGED3. [Table 2-1](#) explains details about the required connections.

Figure 2-1. Buck Converter Components Connection

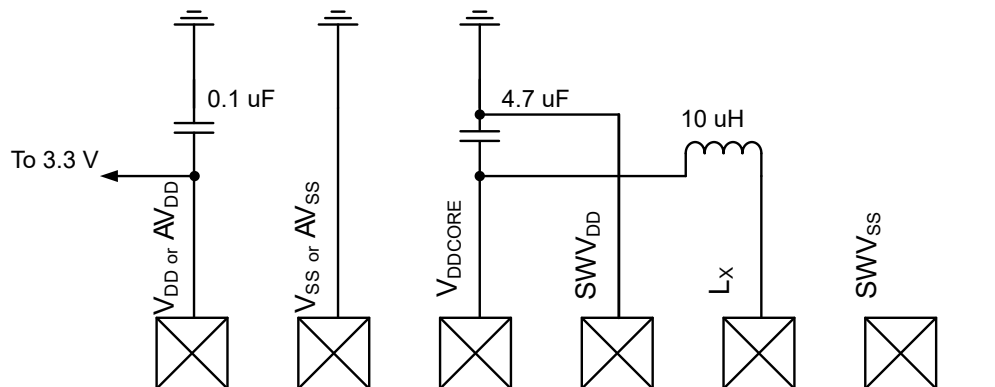


Table 2-1. Pins Used for Programming

Pin Name	Pin Type	Description
V_{DD}/AV_{DD}	Power	Power supply. Must be in 4.5V-5.5V range, and all power pins must be connected. 0.1 μ F bypass capacitors should be connected to these pins.
V_{SS}/AV_{SS}	Power	Ground (GND). All ground pins must be connected.
L_X	Buck converter	10 μ H inductor must be connected between L_X and V_{DDCORE} pins.
V_{DDCORE}	Buck converter	4.7 μ F capacitor should be connected between V_{DDCORE} pin and ground. 10 μ H inductor must be connected between L_X and V_{DDCORE} pins.
SWV_{DD}	Buck converter	Connect to V_{DD}/AV_{DD} .
SWV_{SS}	Buck converter	Connect to GND, between 4.7 μ F capacitor and GND on V_{DDCORE} pin.
$\overline{MCLR}$	Input	Target device Reset/programming enable.
PGECx	Input	ICSP programming clock, where 'x' is the programming pair number.
PGEDx	Input/Output	ICSP programming data, where 'x' is the programming pair number.

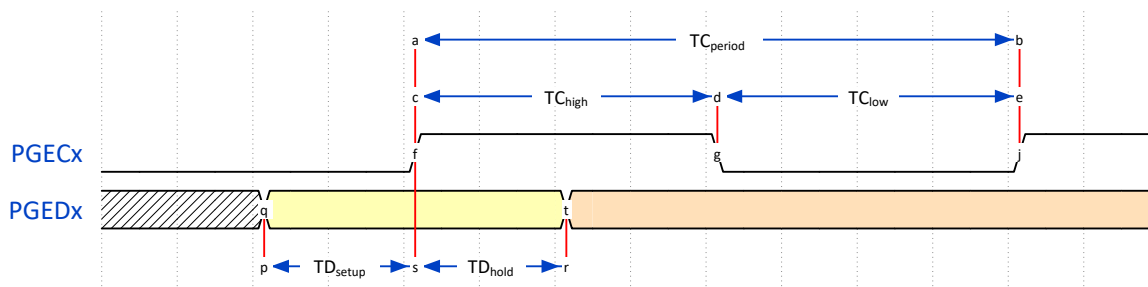
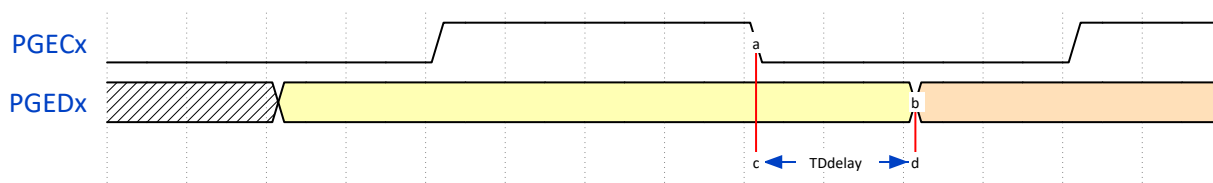
CMOS logic thresholds apply to $\overline{MCLR}$ and the PGECx/PGEDx signals as specified in [Table 2-2](#).

Table 2-2. Electrical Specification for the Programming Interface Signals

Parameter	Min.	Max.	Description
V_{IL}	V_{SS}	$0.2 * V_{DD}$	Input low-level voltage
V_{IH}	$0.8 * V_{DD}$	V_{DD}	Input high-level voltage

For all ICSP operations clocking data into the target device, the PGEDx Output state must be valid and stable before the PGECx clock rising edges. All PGEDx data must be presented with the Least Significant bit (LSb) first.

Figure 2-2, Figure 2-3 and Table 2-3 specify the timing for the ICSP interface signals.

Figure 2-2. ICSP™ Interface Signals Timing Parameters (Programmer Driving PGEDx Pin)**Figure 2-3.** ICSP™ Interface Signals Timing Parameters (Target Device Driving PGEDx Pin)**Table 2-3.** ICSP™ Interface Signals Timing Parameters

Parameter	Min.	Max.	Description
TD_{setup}	20 nS	—	Minimum PGEDx data setup time before PGECx rising edge
TD_{hold}	1 nS	—	Minimum PGEDx data hold time after PGECx rising edge
TC_{period}	60 nS	—	Minimum PGECx clock period
TC_{low} or TC_{high}	20 nS	—	Minimum PGECx clock low or high pulse width
TD_{delay}	—	20 nS	Maximum data update delay after PGECx falling edge

Figure 2-4 through Figure 2-6 provide the pin diagrams for the different packages of the dsPIC33AK256MPS306 devices. The detailed pin descriptions can be found in the device data sheet.

Figure 2-4. 36-Pin VQFN/TQFP

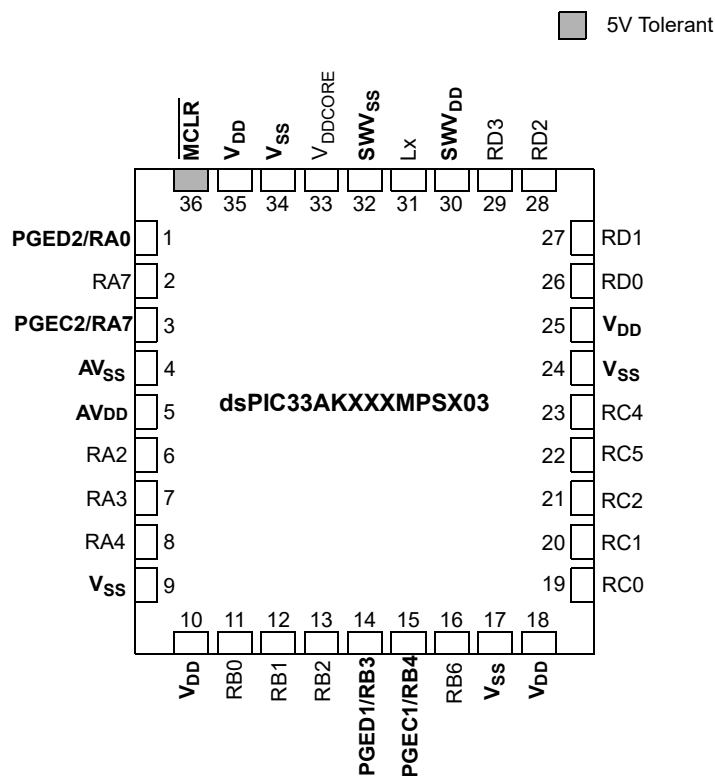


Figure 2-5. 48-Pin VQFN/TQFP

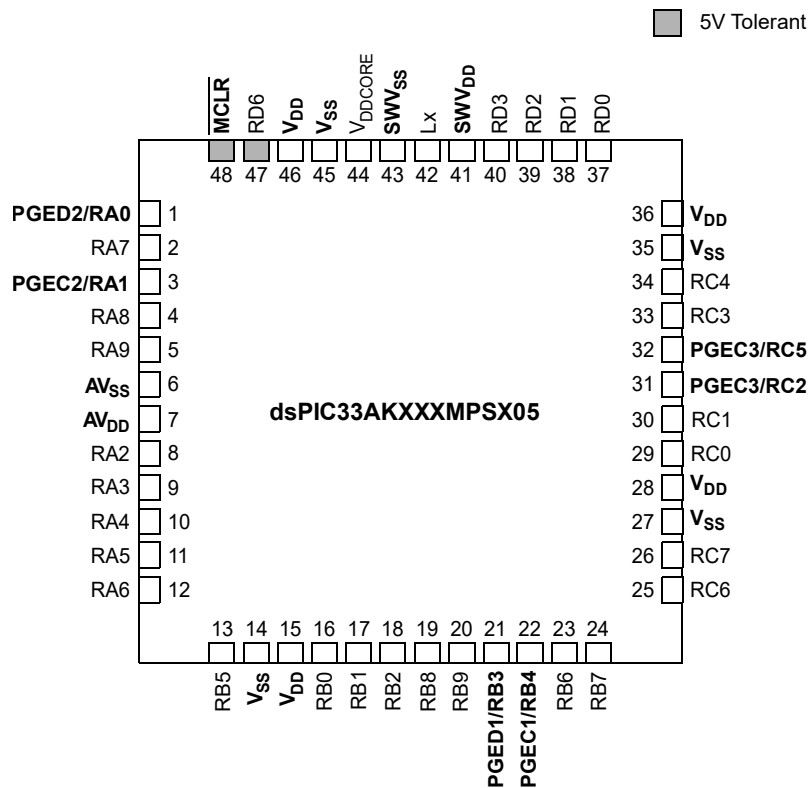
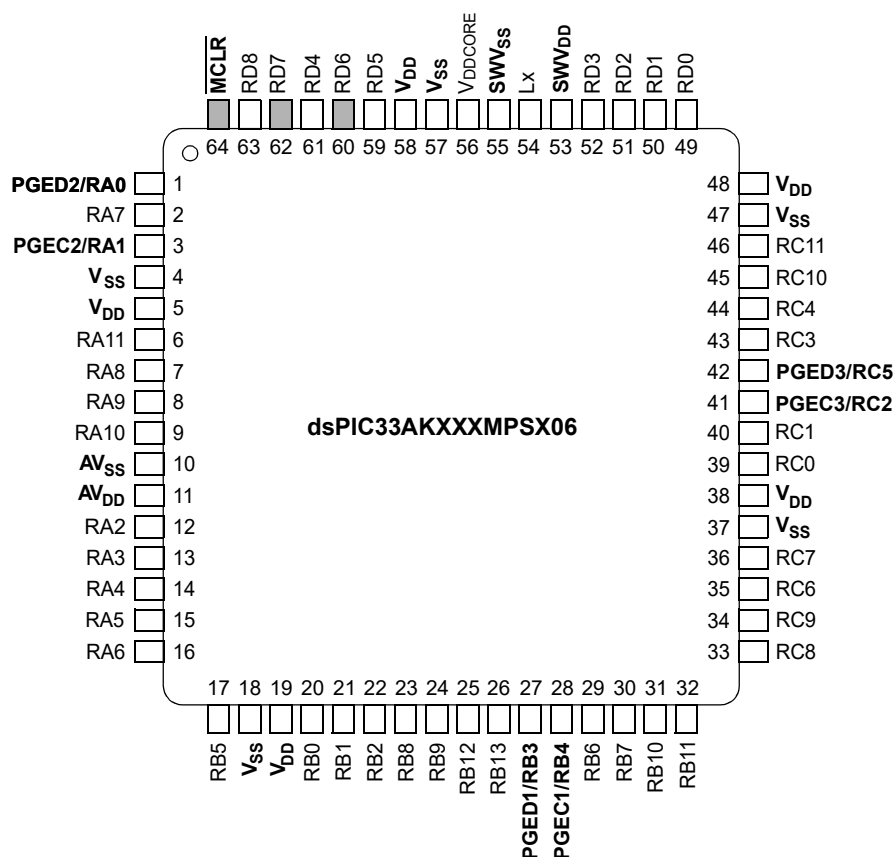


Figure 2-6. 64-Pin TQFP



2.2. ICSP Mode Entry

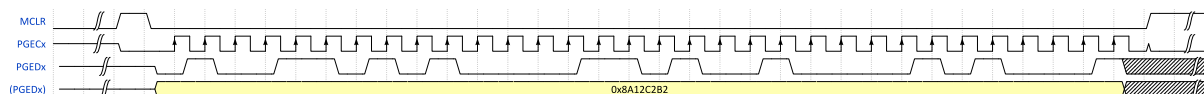
ICSP mode is entered by a specific sequence on the $\overline{\text{MCLR}}$, PGECx and PGEDx pins. PGECx/PGEDx may be selected from the three available pairs (PGEC1/PGED1, PGEC2/PGED2 or PGEC3/PGED3).

To enter ICSP mode, the following steps must be taken:

1. Power the device. V_{DD}/AV_{DD} should remain stable throughout all ICSP operations. Cycling power is not required, so the external programming tool and target chip or circuit may be independently powered; however, a shared V_{SS} ground reference is required.
2. Drive $\overline{\text{MCLR}}$ low.
3. Begin driving PGECx and PGEDx low. PGEDx is a “don't care” at this stage, but to simplify subsequent operations, it should be made an output and driven low.
4. Wait at least 1 ms (no maximum duration).
5. Pulse $\overline{\text{MCLR}}$ high, then low. Pulse duration must be at least 20 ns but should be as short as possible. Long durations allow existing code in the target device's Flash to begin execution. If this user code has RTSP (Run-Time Self-Programming) procedures, then the user's code/RTSP procedures may modify the Flash memory content. In this case, some programmer steps, such as a verification of the programmed Flash data, may fail. Therefore, do not exceed a $\overline{\text{MCLR}}$ high duration of $>2\ \mu\text{s}$ unless it's unavoidable, and even then, try to minimize the dwell time with $\overline{\text{MCLR}}$ high.
6. Generate 32 PGECx clock pulses and simultaneously shift the value, $0x8A12C2B2$, onto the PGEDx pin, the Least Significant bit first. On the wire, if decoded as big-endian octets, this will generate the byte sequence: $0x4D$, $0x43$, $0x48$, $0x51$.

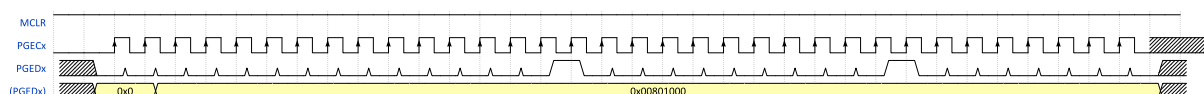
7. After the 32nd falling PGECx clock edge, raise $\overline{\text{MCLR}}$. The ICSP signal waveforms are shown in [Figure 2-7](#).

Figure 2-7. ICSP Entry Sequence Waveforms (PGECx Pulses from 1 to 32)



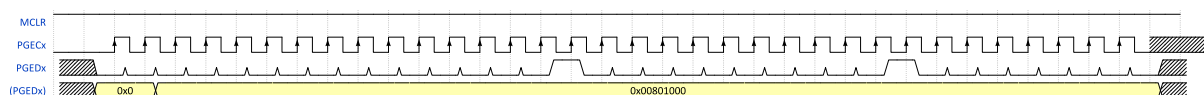
8. Wait at least 500 μs . During this interval, PGECx must remain low, but PGEDx is a “don’t care.”
9. Generate 34 PGECx clock pulses to initialize internal clock selection logic. PGEDx, for these 34 clocks, should be the bit pattern, ‘00’, followed by the 32-bit constant, 0x00801000. The ICSP signal waveforms for this step are shown in [Figure 2-8](#).

Figure 2-8. ICSP Entry Sequence Waveforms (PGECx Pulses from 33 to 66)



10. Generate 34 PGECx clock pulses to set the (not meaningful) CPU Reset vector target. PGEDx, for these 34 clocks, should be the bit pattern, ‘00’, followed by the 32-bit constant, 0x00801000 (same as in Step 9). The ICSP signal waveforms for this step are shown in [Figure 2-9](#).

Figure 2-9. ICSP Entry Sequence Waveforms (PGECx Pulses from 67 to 100)



The programmer should continue to hold $\overline{\text{MCLR}}$ high for all subsequent ICSP operations. ICSP mode will terminate when $\overline{\text{MCLR}}$ is pulled low for 1 ms or longer, or $V_{\text{DD}}/\text{AV}_{\text{DD}}$ is removed.

2.3. ICSP Mode Exit

To exit ICSP mode and begin internal code execution, drive $\overline{\text{MCLR}}$ low, tri-state PGECx and PGEDx, maintain $\overline{\text{MCLR}}$ low for 1 ms and then raise $\overline{\text{MCLR}}$ (preferably tri-state $\overline{\text{MCLR}}$ instead and let an on-board pull-up to V_{DD} decide if user code execution is wanted at this point or not).

Exiting ICSP mode causes a pseudo-POR event internally. Therefore, all SFRs written during the ICSP session will be cleared back to their Reset default states, generally including the SFRs specifically documented as being reset only on POR or BOR-type Resets. RAM state generated during the ICSP session will be retained until the target is power cycled, overwritten by RAM BIST hardware or overwritten by application code execution.

2.4. ICSP Commands

The ICSP command codes notify the target device of the next operation. The codes are followed by a sequence of clocks to shift data into or out from the target. Before issuing any command, the device must first be placed in ICSP mode (refer to [ICSP Mode Entry](#)).

The command codes are a fixed length of two bits, require two PGECx clocks to transfer and are implemented according to [Table 2-4](#).

Table 2-4. ICSP Command Codes

Binary Command	Mnemonic	Operation
00	CMDEXEC	Shifts one 32-bit instruction, two 16-bit instructions or half of a 64-bit instruction into the CPU. The instruction(s) are then executed by the target while receiving the next command and its data.

Table 2-4. ICSP Command Codes (continued)

Binary Command	Mnemonic	Operation
01	CMDRD	Sets the PGEDx pin as an output, shifts 32 bits of data from the VISI register onto the pin and then restores PGEDx as an input for the next command.
10	CMDSEQWR	Sequentially loads 32 bits of data into memory pointed to by W0 on the target, then post-increments W0 by 4. This command internally decomposes the 32 bits of PGEDx shift data into a 64-bit <code>MOV.L</code> instruction executed by the target processor: <code>MOV.L #PGEDx<31:0>, [W0++]</code>
11	CMDSEQRD	Returns the VISI register and internally executes the following instruction: <code>MOV.L [W0++], [W8]</code> When W0 is initialized to a source memory address and W8 contains the address of the VISI register, this command permits sequential memory addresses to be read from the target with minimal overhead.

The 2-bit command code and 32 bits of data transferred into or out from the target are always presented on the wire, the Least Significant bit first.

All command code and data bits, driven onto the PGEDx pin by the programmer, are latched by the target on the rising edge of the PGECx clock. Therefore, the PGEDx state must be valid and stable for at least one setup time before the PGECx rising edge (TD_{setup}) and held in the same state for at least one hold time after PGECx has risen (TD_{hold}).

When reading data from the target, each of the 32 data bits is output/changed on PGEDx by the target on the falling edge of the PGECx clock (still generated by the programmer). The data remain unchanged until the next falling edge, so the programmer should sample the data on or after the rising clock edge, but before it generates another PGECx falling edge.

2.4.1. ICSP Instruction Execution (CMDEXEC)

The Instruction Execution Sequence (CMDEXEC) shifts one 32-bit instruction, two 16-bit instructions or half of a 64-bit instruction into the target CPU.

The Instruction Execution Sequence is:

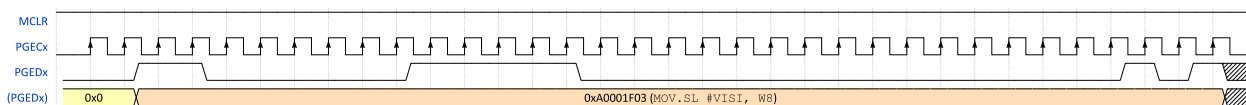
1. The programmer shifts the '00' bits into the device.
2. Then, the programmer sends 32 bits of instruction opcode data to the device. Each PGEDx bit is latched by the device on the rising edge of the PGECx pulse. The CPU executes the instruction(s) over the next 5-10 PGECx clocks while sending the next ICSP command.

When providing 16-bit instruction(s), the first 16-bit instruction to execute must be aligned to the Least Significant 16 bits and followed by another 16-bit instruction in the upper half of the 32-bit data transfer. If only one 16-bit instruction is available, it must be aligned in the low 16 bits and zero-extended out to 32 bits (upper 16 bits encode a NEOP).

When executing a 64-bit instruction, the first CMDEXEC Sequence will load the first instruction word (bits 0-31 of the opcode). A second CMDEXEC Sequence must be issued to load the second instruction word (bits 32-63 of the opcode) and allow the CPU to begin executing the instruction. For 64-bit instructions, the second CMDEXEC Sequence must be sent after the first CMDEXEC Sequence without any other intervening ICSP commands. Otherwise, the CPU's instruction flow will be corrupted and an Illegal Opcode Reset may be generated.

Figure 2-10 shows an example where the “MOV.SL #VISI, W8” instruction (load the VISI register address into the W8 register), with opcode 0xA0001F03, is shifted into the CPU.

Figure 2-10. CMDEXEC Sequence Where MOV.SL #VISI, W8 with 0xA0001F03 Opcode is Shifted Into the CPU



2.4.2. ICSP Read of VISI Register (CMDRD)

This command shifts the content of the VISI register onto the PGEDx pin for capture by the programmer. When combined with an Instruction Execution Sequence (CMDEXEC) that writes to VISI, it may be used to read status registers and memory content from the target device.

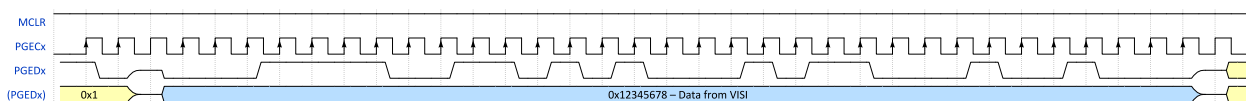
The read of VISI Register Sequence is:

1. The programmer shifts the '01' bits into the device. As all data follow the Least Significant bit first ordering, the '1' bit must be presented on the PGEDx wire before the '0' bit.
2. One Idle PGECx clock is generated by the programmer to accommodate switching the PGEDx pin direction. The programmer should tri-state PGEDx before the falling edge of this clock, as the target device will begin driving bit 0 of VISI at this time.
3. The programmer shifts in the 32-bit VISI register content from the device. The Least Significant bit of the VISI register is presented first. The device updates each data bit on the falling edge of the PGECx pulse. To accommodate propagation delay of the clock into the device and output delay returning the next bit, the programmer should sample the data from the device on or after the PGECx rising edge.
4. One Idle PGECx clock is generated by the programmer to accommodate switching the PGEDx pin direction back to an input. The device tri-states PGEDx on the falling edge that completes the VISI bit 31 transfer, so the programmer can begin driving PGEDx anytime during or at the end of this clock.

All Instruction Execution Sequences (CMDEXEC) that write to the VISI register do not complete execution until several clocks belonging to the next command have been presented. Therefore, any operation that writes to VISI will not have taken effect if immediately followed by a read of the VISI Register Sequence (CMDRD). Placing an operation that writes to VISI immediately before a read of the VISI Register Sequence (CMDRD) will still execute normally, but the data returned will be delayed (will contain old VISI data). To receive the up-to-date VISI content moved by the preceding CMDEXEC Sequence, a second CMDEXEC, with any opcode, should be executed before the CMDRD Sequence.

Figure 2-11 shows an example of the CMDRD Sequence where the 0x12345678 data are shifted out from the VISI register to the programmer.

Figure 2-11. CMDRD Data Sequence with Data Shifted out from VISI Register to Programmer



2.4.3. ICSP Sequential Write (CMDSEQWR)

The ICSP Sequential Write Sequence (CMDSEQWR) permits rapid writes of 32-bit data via an indirect pointer access to RAM or device registers. When the sequence is completed, a 64-bit MOV.L instruction is internally generated, encoding all 32 bits of shifted data and passed to the CPU for execution. The outcome is equivalent to issuing two CMDEXEC Sequences necessary to execute a 64-bit instruction of:

```
MOV.L #PGEDx<31:0>, [W0++]
```

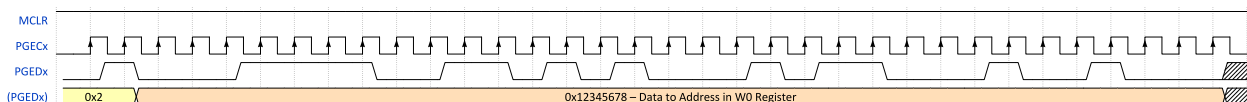
This instruction writes the 32 bits of provided data to the memory pointed to by the 4-byte aligned address in the W0 register, then increments the W0 pointer by four. By pre-initializing W0 to a RAM or register address, incrementing locations may be written to, with minimal overhead, simply by executing a series of back-to-back **CMDSEQWR** Sequences. Generally, **CMDSEQWR** should be used for all data writes of four or more bytes from the programmer to 4-byte aligned sequential addresses.

The Sequential Write Sequence is:

1. The programmer shifts the '10' bits into the device. As all data follow the Least Significant bit first ordering, the '0' bit must be presented on the PGEDx wire before the '1' bit.
2. Then, the programmer sends 32 bits of RAM or SFR data to the device. Each PGEDx bit is latched by the device on the rising edge of the PGECx pulse. The CPU executes the generated **MOV.L** instruction over the next 5-10 PGECx clocks while sending the next ICSP command.

Figure 2-12 shows an example of the **CMDSEQWR** Sequence, where 0x12345678 from the programmer is written to the address in the W0 register.

Figure 2-12. **CMDSEQWR** Sequence Where Data from Programmer are Written to Address in W0 Register



2.4.4. ICSP Sequential Read (**CMDSEQRD**)

This Sequential Read Sequence shifts out the 32-bit VISI register content onto the PGEDx pin, identically to **CMDDRD**, but will internally also execute the following instruction:

```
MOV.L [W0++], [W8]
```

The existing VISI content is buffered before execution of this **MOV.L** instruction, so all 32 bits of VISI appear on PGEDx as they existed before this instruction is executed. However, this instruction is typically used to reload VISI with more data from SFRs, RAM or program space, and it completes execution by the time all bits have shifted out. Therefore, **CMDSEQRD** is optimized for use in a loop to transfer multiple sequential memory contents out of the target and into the programmer.

As the generated **MOV.L** instruction references W0 and W8, this command must be preceded with **CMDEXEC** commands to load W8 with the address of the VISI register and W0 with the read address on the target:

```
MOV.SL #VISI, W8
```

```
MOV.SL #ReadAddress<23:0>, W0
```

The Sequential Read Sequence is:

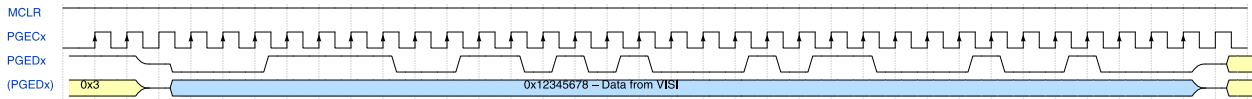
1. The programmer shifts the '11' bits into the device.
2. One Idle PGECx clock is generated by the programmer to accommodate switching the PGEDx pin direction; the programmer should tri-state PGEDx before the falling edge of this clock, as the target device will begin driving bit 0 of VISI at this time.
3. The programmer shifts in the 32-bit VISI register content from the device. The Least Significant bit of the VISI register is presented first. The device updates each data bit on the falling edge of the PGECx pulse. To accommodate propagation delay of the clock into the device and output delay returning the next bit, the programmer should sample the data from the device on or after the PGECx rising edge.
4. One Idle PGECx clock is generated by the programmer to accommodate switching the PGEDx pin direction back to an input; the device tri-states PGEDx on the falling edge that completes the VISI

bit 31 transfer, so the programmer can begin driving PGEDx anytime during or at the end of this clock.

Unlike CMDEXEC and CMDSEQWR, the CPU will finish execution of the internally generated `MOV .L [W0++], [W8]` instruction before the final (buffered) bit 31 of VISI is shifted out. This permits back-to-back reissuing of CMDSEQRD to return the next 32 bits of memory without extra clocking following the VISI write.

Figure 2-13 shows an example of CMDSEQRD, where the 0x12345678 data are received by a programmer from VISI.

Figure 2-13. Example of CMDSEQRD Where the Data are Received by a Programmer from VISI



3. Programming Procedures

The dsPIC33AK256MPS306 family devices' programming flow consists of the following steps:

1. Enter ICSP mode
2. Bulk Erase entire Flash:
 - a. Enter ICSP mode
 - b. Bulk Erase
 - c. Exit ICSP mode
3. Program FBOOT_BACKUP and FBOOT:
 - a. Enter ICSP mode
 - b. Program FBOOT_BACKUP
 - c. Exit ICSP mode
 - d. Enter ICSP mode
 - e. Program FBOOT
 - f. Exit ICSP Mode
4. Write code memory
5. Read back CRC to verify the code memory
6. Write User Configuration A1 backup memory:
 - a. Read back and verify
 - b. Write User Configuration B backup memory
 - c. Read back and verify
7. Write User Configuration A1 primary memory:
 - a. Read back and verify
 - b. Write User Configuration B primary memory
 - c. Read back and verify
8. Exit ICSP mode

If the programming or erase operations are disabled in Configuration Words of UCAX and UCB areas, then the Flash erase or write procedures will fail with no effect for the protected areas. To erase all Flash memory, the protected regions defined in the UCB area must be disabled by erasing UCB and exiting/re-entering ICSP mode.

The following steps should be done to remove the code protection:

1. Enter ICSP mode
2. Bulk Erase to erase UCAX memory, including the code protection bits of UCB memory
3. Exit ICSP mode to reload Configuration Words
4. Enter ICSP mode
5. Bulk Erase to erase UCB memory, including the code protection bits. This procedure will also erase the entire Code Flash memory.
6. Exit ICSP mode to reload Configuration Words

When the Code Flash memory is not protected from programming or erase, then the Bulk Erase does a parallel erase operation and completes quickly (refer to the data sheet for the Bulk Erase time). Conversely, if any erase, write or OTP protected regions are defined in the Code Flash, then the Bulk Erase command will still be accepted; however, internally, the NVM controller will perform

the Bulk Erase as a self-iterated sequential Page Erase, resulting in a many times longer Bulk Erase time.

3.1. Bulk Erase

This algorithm erases the user Flash memory and the UCAx and UCB User Configuration pages. User OTP is retained and can never be erased. If hardware write-protect functions have been enabled in the UCAx and UCB page contents, the UCAx and UCB pages and arbitrary Flash address ranges defined by security region descriptors in UCB may also be permanently retained and will survive Bulk Erase.

Table 3-1. Bulk Erase Algorithm

ICSP Sequence	ICSP Command Code	Data/Opcode	Instruction Executed
Step 1: Initialize pointers. Move VISI address to W8 and NVMCON address to W9.			
CMDEXEC	00	0xA0001F03	MOV.SL #VISI, W8
CMDEXEC	00	0xA400C003	MOV.SL #NVMCON, W9
Step 2: Write 0x400E to NVMCON to set up for the Bulk Erase NVM operation.			
CMDEXEC	00	0x8A9004E1	MOVS.W #0x400E, [W9]
Step 3: Set WR bit (NVMCON[15]) to start the NVM operation and move NVMCON to VISI.			
CMDEXEC	00	0x8E9004E1	MOVS.W #0xC00E, [W9]
CMDEXEC	00	0x83892400	MOV.L [W9], [W8]
Step 4: Provide clocks to complete execution of the prior move of NVMCON to VISI by executing a second move of NVMCON to VISI, then shift VISI on PGEDx.			
CMDEXEC	00	0x83892400	MOV.L [W9], [W8]
CMDRD	01	VISI	
Step 5: Repeat Step 4 to poll WR bit (NVMCON[15]) until it is clear, indicating completion.			

3.2. Page Erase

This algorithm ([Table 3-2](#)) erases one page of the Code Flash memory. The erase address is page-size aligned, and “don’t care” bits are its least significant part. The Page Erase procedure does not have an effect on the User OTP memory. If FPED or Code-Protect have been enabled, Page Erase will have no effect on the User Configuration A and B areas. Like Bulk Erase, the Page Erase command may have no effect when targeting the UCAx page, UCB page or an address range with a security descriptor defining the page as hardware write-protected.

Table 3-2. Page Erase Algorithm

ICSP Sequence	ICSP Command Code	Data/Opcode	Instruction Executed
Step 1: Initialize pointers. Move VISI address to W8 and NVMCON address to W9.			
CMDEXEC	00	0xA0001F03	MOV.SL #VISI, W8
CMDEXEC	00	0xA400C003	MOV.SL #NVMCON, W9
Step 2: Move NVMCON address to W0.			
CMDEXEC	00	0x00000309	MOV.L W9, W0
Step 3: Write 0x4003 to NVMCON to set up for the Page Erase NVM operation.			
CMDSEQWR	10	0x00004003	MOV.L #PGEDx<31:0>, [W0++]
Step 4: Initialize NVMADR with any address on the target page.			
CMDSEQWR	10	EraseAddress[31:0]	MOV.L #PGEDx<31:0>, [W0++]
Step 5: Set WR bit (NVMCON[15]) to start the NVM operation and move NVMCON to VISI.			
CMDEXEC	00	0x8E900431	MOVS.W #0xC003, [W9]
CMDEXEC	00	0x83892400	MOV.L [W9], [W8]
Step 6: Provide clocks to complete execution of the prior move of NVMCON to VISI by executing a second move of NVMCON to VISI, then shift VISI on PGEDx.			

Table 3-2. Page Erase Algorithm (continued)

ICSP Sequence	ICSP Command Code	Data/Opcode	Instruction Executed
CMDEXEC	00	0x83892400	MOV.L [W9], [W8]
CMDRD	01	VISI	
Step 7: Repeat Step 6 to poll WR bit (NVMCON[15]) until it is clear, indicating completion.			

3.3. Quadword Program

This algorithm (Table 3-3) programs one 16-byte aligned quadword. The Least Significant four bits of the destination address are “don't care” bits when written and will be forced to zeros for the programming operation. The Flash memory on these devices has a built-in Error Correcting Code (ECC) mechanism. The ECC checksum is calculated during write operations and stored, unmapped, alongside each quadword. If the same Flash quadword is programmed more than one time without an intermediate erase cycle, this ECC checksum becomes corrupted. Subsequently, when the location with a corrupted checksum is read, an ECC error interrupt or trap will be generated. After the Flash is erased, the programmer must not write to any Flash quadword location (including OTP areas) more than one time.

Table 3-3. Quadword Programming Algorithm

ICSP Sequence	ICSP Command Code	Data/Opcode	Instruction Executed
Step 1: Move VISI address to W8 and NVMCON address to W9.			
CMDEXEC	00	0xA0001F03	MOV.SL #VISI, W8
CMDEXEC	00	0xA400C003	MOV.SL #NVMCON, W9
Step 2: Initialize W0 with an NVMCON address for sequential loading. Load the NVMCON value with WR bit set in W10. Write 0x4001 in NVMCON to set up for Quadword Programming.			
CMDEXEC	00	0x00000309	MOV.L W9, W0
CMDEXEC	00	0xA8030007	MOV.SL #0xC001, W10
CMDSEQWR	10	0x00004001	MOV.L #PGEDx<31:0>, [W0+]
Step 3: Load the destination address in NVMADR.			
CMDSEQWR	10	Destination Address[31:0]	MOV.L #PGEDx<31:0>, [W0+]
Step 4: Load data in the NVM Controller Data registers (NVMDATA0, NVMDATA1, NVMDATA2 and NVMDATA3).			
CMDSEQWR	10	Data[31:0]	MOV.L #PGEDx<31:0>, [W0+]
CMDSEQWR	10	Data[63:32]	MOV.L #PGEDx<31:0>, [W0+]
CMDSEQWR	10	Data[95:64]	MOV.L #PGEDx<31:0>, [W0+]
CMDSEQWR	10	Data[127:96]	MOV.L #PGEDx<31:0>, [W0+]
Step 5: Restore W0 with NVMCON's address. Set WR bit (NVMCON[15]) to start the NVM operation. Move NVMCON to VISI.			
CMDEXEC	00	0x1F0A0309	MOV.L W9, W0
			MOV.L W10, [W0++]
CMDEXEC	00	0x83892400	MOV.L [W9], [W8]
Step 6: Move NVMCON to VISI. Shift VISI on PGEDx.			
CMDEXEC	00	0x83892400	MOV.L [W9], [W8]
CMDRD	01	VISI	
Step 7: Repeat Step 6 to poll WR bit (NVMCON[15]) until it is clear, indicating completion.			
Step 8: Repeat Steps 3-7 until all sequential quadwords have been programmed.			

3.4. Row Program

This algorithm (Table 3-4) programs one or more Flash rows. The row data will be preloaded into the device's RAM. While the NVM controller programs/transfers the data from RAM to Flash, an additional row of data can be moved into device RAM for a subsequent Row Programming operation. By overlapping the transfer of data from the programmer to the device RAM, and from the device RAM to Flash via the NVM controller, this programming algorithm attains maximal programming throughput approaching the raw clocking rate of the PGECx/PGEDx pins. This

operation should always be used when the source data are suitably aligned and big enough to define at least one row.

The Flash memory on these devices has a built-in Error Correcting Code (ECC) mechanism. The ECC checksum is calculated during a write operation and stored with data in Flash. If the Flash memory is programmed more than one time, this ECC checksum becomes corrupted. Next time, when the location with a corrupted checksum will be accessed, a single-bit ECC error interrupt or double-bit ECC error trap may be generated. After the Flash is erased, the programmer must not write to any Flash location (including OTP areas) more than one time.

The Row Programming is disabled for User Configuration A and B areas and will not have an effect on them.

Table 3-4. Row Programming Algorithm

ICSP Sequence	ICSP Command Code	Data/Opcode	Instruction Executed
Step 1: Initialize pointers. Move VISI address to W8 and NVMCON address to W9.			
CMDEXEC	00	0xA0001F03	MOV.SL #VISI, W8
CMDEXEC	00	0xA400C003	MOV.SL #NVMCON, W9
Step 2: Set W1 to a starting address in RAM (0x4000), then duplicate this pointer in W0 for CMDSEQWR use. Initialize NVMCON with 0x4002 to set up for Row Programming.			
CMDEXEC	00	0x84010003	MOV.SL #0x4000, W1
CMDEXEC	00	0x00000301	MOV.L W1, W0
CMDEXEC	00	0x8A900421	MOVS.W #0x4002, [W9]
Step 3: Load data into the RAM buffer.			
CMDSEQWR	10	Data[31:0]	MOV.L #PGEDx<31:0>, [W0++]
Step 4: Repeat Step 3 until all row data are moved to the RAM buffer. 128 total CMDSEQWR commands must be issued, each generating 32 bits of data for ascending RAM locations.			
Step 5: To prepare for WR bit polling, move NVMCON to VISI.			
CMDEXEC	00	0x83892400	MOV.L [W9], [W8]
Step 6: Move NVMCON to VISI. Shift VISI on PGEDx.			
CMDEXEC	00	0x83892400	MOV.L [W9], [W8]
CMDRD	01	VISI	
Step 7: Repeat Step 6 to poll WR bit (NVMCON[15]) until it is clear, indicating completion of the previous Row Programming operation.			
Step 8: Write the target Flash row address to NVMADR, the RAM source address to NVMSRCADR and then set WR bit (NVMCON[15]) to begin hardware Row Programming.			
CMDEXEC	00	0x94030195	MOV.L W1, NVMSRCADR
CMDEXEC	00	0x8000C013	MOV.SL #NVMADR, W0
CMDSEQWR	10	Destination Address[31:0]	MOV.L #PGEDx<31:0>, [W0++]
CMDEXEC	00	0x8E900421	MOVS.W #0xC002, [W9]
Step 9: Change the RAM buffer address to continue data loading while NVM controller programs the previous buffer. The address will be switched between 0x4000 and 0x4200. Load the new starting address of the RAM buffer to W0.			
CMDEXEC	00	0x03014491	BTG.L W1, #9
			MOV.L W1, W0
Step 10: Repeat Steps 3-9 for any additional rows of data available for programming.			
Step 11: To prepare for WR bit polling for the last Row Programming, move NVMCON to VISI.			
CMDEXEC	00	0x83892400	MOV.L [W9], [W8]
Step 12: Move NVMCON to VISI. Shift VISI on PGEDx.			
CMDEXEC	00	0x83892400	MOV.L [W9], [W8]
CMDRD	01	VISI	
Step 13: Repeat Step 12 to poll WR bit (NVMCON[15]) until it is clear, indicating programming completion for the last row.			

3.5. Read Memory

This algorithm (Table 3-5) may be used to read from any implemented memory space, including DEVID, DEVREV, device registers, RAM, User Flash, User OTP, UCAx and UCB Configuration Words and SFRs. A 32-bit aligned read address is required.

Attempts to read from unimplemented memory, reserved addresses, regions protected by code-protect or persistent security restrictions defined by UCB security region descriptors will return zero.

Table 3-5. Read Memory Algorithm

ICSP Sequence	ICSP Command Code	Data/Opcode	Instruction Executed
Step 1: Initialize Transfers Destination Pointer (W8) to the VISI register.			
CMDEXEC	00	0xA0001F03	MOV.SL #VISI, W8
Step 2: Initialize pointer to read from.			
CMDEXEC	00	0x80000003 (Read Address [23:0] << 2)	MOV.SL #ReadAddress<23:0>, W0
Step 3: Issue a dummy CMDSEQRD to copy the first read data into VISI. Throw the data returned by this dummy operation away as they are the existing contents of VISI, not the data read from Read Address[23:0].			
CMDSEQRD	11	VISI	MOV.L [W0++], [W8]
Step 4: Read the VISI register using CMDSEQRD.			
CMDSEQRD	11	VISI	MOV.L [W0++], [W8]
Step 5: Repeat Step 4 until all sequential data have been read from the target device. To update the address for a random access, return to Step 2.			

3.6. CRC Checksum Calculation

This algorithm (Table 3-6) calculates the 32-bit Cyclic Redundancy Check (CRC) checksum of the Flash memory region. This checksum can be used to verify the written data in the previous programming steps or verify if the existing Flash contents match a known pattern, but which cannot be directly read due to code-protect or security restrictions defined in UCAX or UCB. For details about the CRC calculation algorithm, refer to [Flash Memory Controller](#).

The NVM controller CRC calculation can be disabled by Configuration Words in the User Configuration A and B areas.

Table 3-6. CRC Checksum Calculation Algorithm

ICSP Sequence	ICSP Command Code	Data/Opcode	Instruction Executed
Step 1: Move VISI address to W8 and NVMCRCCON address to W9. Set the CRCEN bit (NVMCRCCON[15]) to enable CRC hardware.			
CMDEXEC	00	0x9C00C163	MOV.SL #NVMCRCDATA, W7
CMDEXEC	00	0xA0001F03	MOV.SL #VISI, W8
CMDEXEC	00	0xA400C123	MOV.SL #NVMCRCCON, W9
CMDEXEC	00	0xC2F92008	BSET.L [W9], #15
Step 2: Load the start address in the NVMCRCST register, the end address in the NVMCRCEND register and the initial value in the NVMCRCSEED register.			
CMDEXEC	00	0x8000C133	MOV.SL #NVMCRCST, W0
CMDSEQWR	10	Start Address[31:0]	MOV.L #PGEDx<31:0>, [W0++]
CMDSEQWR	10	End Address[31:0]	MOV.L #PGEDx<31:0>, [W0++]
CMDSEQWR	10	Initial Value[31:0]	MOV.L #PGEDx<31:0>, [W0++]
Step 3: Set the START bit (NVMCRCCON[14]) to start the CRC calculation. Prepare for polling by moving NVMCRCCON to VISI.			
CMDEXEC	00	0xC2E92008	BSET.L [W9], #14
CMDEXEC	00	0x83892400	MOV.L [W9], [W8]
Step 4: Move NVMCRCCON to VISI. Shift VISI on PGEDx.			
CMDEXEC	00	0x83892400	MOV.L [W9], [W8]
CMDRD	01	VISI	
Step 5: Repeat Step 4 to poll the START bit (NVMCRCCON[14]) until it is clear, indicating completion.			
Step 6: Move NVMCRCOUT to VISI. Shift VISI on PGEDx.			
CMDEXEC	00	0x83872400	MOV.L [W7], [W8]
CMDEXEC	00	0x00000000	NOP
CMDRD	01	VISI	

4. Revision History

Revision A (March 2024)

Original version of the programming specification created for the dsPIC33AK256MPS306 device family.

Revision B (June 2026)

Updated **1.4. Configuration Bits, 1.5. Flash Memory Protection, 1.5.2. User Configuration A and B Areas Protection, 1.5.3. Entire Flash Protection, 3. Programming Procedures, 3.1. Bulk Erase, 3.2. Page Erase, 3.5. Read Memory and 3.6. CRC Checksum Calculation.**

Added **Programming the FBOOT Configuration Register, Dual Partition Flash Programming Considerations, Dual Partition Memory Organization, Dual Boot Sequence Number, Erase Operation with Dual Partition Flash, Programming in Dual Partition Mode and Programming in Dual Partition Mode.**

Updated **Table 1-1. Flash Memory Map, Table 1-3. Programming Operations and Table 1-10. Flash Operations Maximum Time.**

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